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PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of Joseph Fjelstad	:	Group Art Unit: 2811
Application Serial No. 09/020,647	:	Examiner: Unassigned
Filed: February 9, 1998	:	Date: July 21, 2000
For: **METHOD OF MAKING A SEMICONDUCTOR CHIP PACKAGE**	:	

Assistant Commissioner For Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed January 25, 2000, please amend the above-identified application as follows:

In the Claims:

Please amend claims 1, 4, 6, 21 and 28 as follows:

1. (Amended) A method of creating a compliant semiconductor chip package assembly comprising the steps of:

providing a first dielectric protective layer on a contact bearing surface of a semiconductor chip, wherein the semiconductor chip has a central region bounded by chip contacts of the semiconductor chip and wherein the dielectric protective layer has a plurality of apertures such that the chip contacts are exposed;

providing a compliant layer atop the first dielectric protective layer within the central region, wherein said compliant layer has a substantially flat top surface, a bottom surface that is attached to the first dielectric protective layer and sloping edges between the top surface and the bottom surface; and

selectively electroplating elongated bond ribbons atop the first dielectric protective layer and the compliant layer wherein each bond ribbon electrically connects each

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on July 21, 2000.

(Signature)
MICHAEL J. DOHERTY
Typed or Printed Name of Person Signing Certificate